

Thermal Interface Material



KL 91



- Ceramic filled adhesive
- Acrylate film with fiberglass
- Mechanical fastener required

Applications

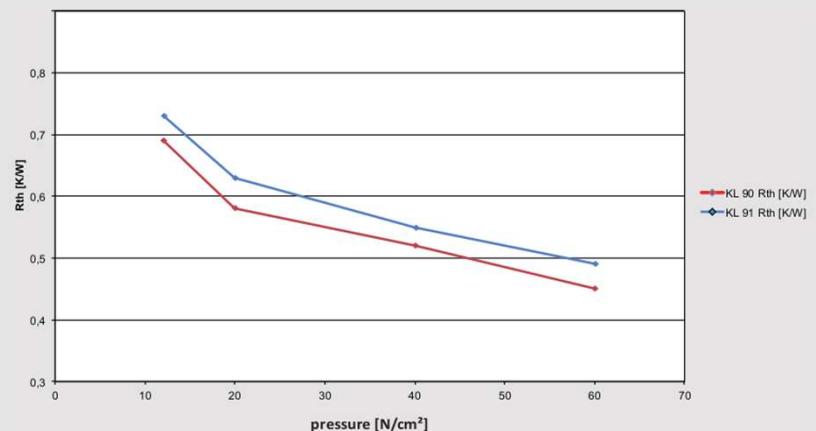
- CPU
- LED
- Flip Chip, DSP
- BGA, PPGA
- MOSFET on heat sinks

Options

- KL91 has a shelf life of 12 months after day of manufacture

Properties	Unit	KL 91
Color		Black
Thermal Properties		
Thermal Conductivity	W/mK	1.35
Thermal Resistance	K/W	0.55
Electrical Properties		
Breakdown Voltage $U_{d; ac}$	kV	6
Dielectric Breakdown $E_{d; ac}$	kV/mm	20
Volume Resistivity	Ωm	$2.6 \cdot 10^4$
Dielectric Constant		18.5
Dielectric Loss Factor $\tan \delta$		$3.1 \cdot 10^{-1}$
Mechanical Properties		
Hardness	Shore A	59
Tensile Strength	N/mm ²	11.28
Physical Properties		
Application Temperature	°C (°F)	-40 to +125 (-40 to +257)
Density	g/cm ³	1.87
Total Mass Loss	Ma. %	<0.15
Flame rating	UL-94	V-0
Possible Thickness	mm (inch)	0.3 (0.012)

Compression KL 90 & KL 91



The data provide engineering guidance, performance in actual applications should be established through testing.